

IN THE CLAIMS:

Please amend Claims 1 and 3 to 8, as shown below.

1. (Currently Amended) A printed wiring board comprising:

a substrate having two opposite surfaces and a plurality of soldering through holes formed in said ~~substrate, substrate, wherein~~ each of said plurality of soldering through holes ~~opens~~ opening in said opposite surfaces for inserting leads of an inserted component to be mounted onto the printed wiring board and for soldering said leads of an inserted component onto said substrate,

wherein each of said plurality of soldering through holes has an inner peripheral surface and a pair of lands, each land of said pair of lands being each formed on respective ones of ~~continuously across~~ said opposite surfaces ~~therewith and formed~~ continuously over said inner peripheral surface,

wherein at least one land of said pair of lands is connected to at least one wiring pattern at a connection portion;

~~said printed wiring board further comprising:~~

~~connection state maintaining means for maintaining wherein~~ said connection portion is maintained in a state not wetted by ~~solder~~ solder; and

wherein, except for said connection portion, for maintaining said at least one land of said pair of lands is maintained ~~, except for said connection portion,~~ in a state wetted by solder.

2. (Cancelled)

3. (Currently Amended) A printed wiring board as claimed in claim 1, wherein said connection portion is maintained in a state not wetted by solder using state maintaining means comprises a material not wetted by the solder coated onto said pair of lands.

4. (Currently Amended) A printed wiring board as claimed in claim 3, wherein the material not wetted by the solder is a solder resist.

5. (Currently Amended) A printed wiring board as claimed in claim 3, wherein the material not wetted by the solder is a silk-screen pattern.

6. (Currently Amended) A printing wiring board as claimed in claim 3, wherein the material not wetted by the solder comprises a solder resist and a silk-screen pattern laminated onto each other.

7. (Currently Amended) A printed wiring board as claimed in claim 1, wherein said connection portion is maintained in a state not wetted by solder using state maintaining means comprises deactivation treatment means for oxidizing at least a part of the surface of at least one land of said pair of lands.

8. (Currently Amended) A printed wiring board as claimed in claim 1, wherein lead solder is applied to the leads of the inserted component prior to insertion of said leads of the inserted component into said through-holes of said printed wiring board.

9. (Original) A printed wiring board as claimed in claim 1, wherein the inserted component is soldered onto said substrate by flow soldering using lead-free solder.

10. (Previously Presented) A printed wiring board as claimed in claim 9, wherein the lead-free solder contains Bismuth.

11. (Cancelled)